



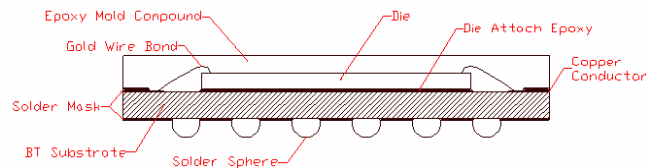
DieScale™ CSP Datasheet

In response to the growing demand for the smallest possible packaged device, Chip Supply offers DieScale™ CSP. DieScale™ packages are offered in laminate format and are available as Ball Grid Arrays with ball pitches of 0.5mm to 1.27mm.

Chip Supply's DieScale™ packaging uses standard assembly technology and process flows. Established SMT processes and techniques are compatible. DieScale™ package size and design provides an ideal solution for high speed applications requiring a small footprint. Also, the DieScale™ CTE properties are compatible with standard FR-4 applications.

Process Specifications:

• Die Thickness	15 mils max
• Minimum Bond Pitch	3.0 mils
• Marking	Transfer
• Ball Inspection	Production 100%
• Wafer Bumping	Available
• Wafer Backgrinding	Available
• Substrate	
– Dielectric	BT-Laminate
– Conductor	Copper, Nickel, Gold
– Layers	2 to 4 layers
• Spheres	Eutectic (63Sn/36Pb/2Ag)
• Encapsulation	Epoxy Mold Compound
• Shipping	Tape and Reel Waffle Packs Custom Trays



Test Services:

- Program Generation
- Product Engineering
- Wafer Sort
- Wafer Inspection
- Various Test Systems
- Burn-in

Features:

DieScale™ designs and package offerings provide a range of package formats for prototype-to-production applications.

- <0.12mm (5 mil) co planarity
- BT (Bismaleimide-Triazine)
- Full, in-house design capability
- Square or rectangular package options

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